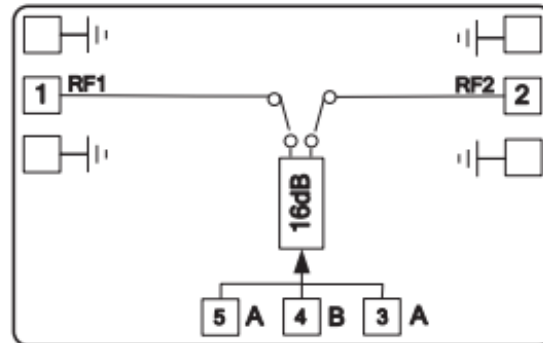


Features

- Attenuation Range: 15.25dB
- Attenuation Accuracy: ± 0.6 dB
- Insertion Loss : 1dB
- Impedance: 50 Ω
- Die Size: 1.0 x 1.0 x 0.1 mm

Typical Applications

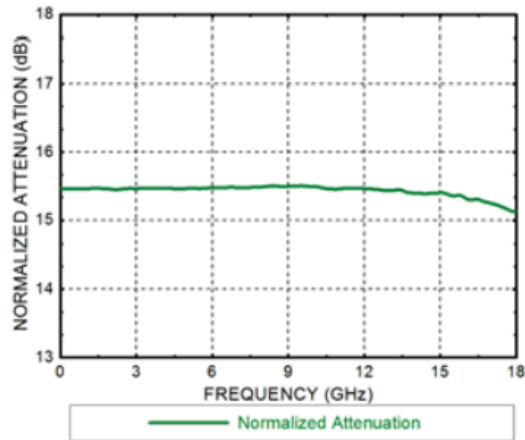
- Test Instrumentation
- Microwave Radio & VSAT
- Military & Space
- Telecom Infrastructure
- Fiber Optics

Functional Block Diagram

Electrical Specifications

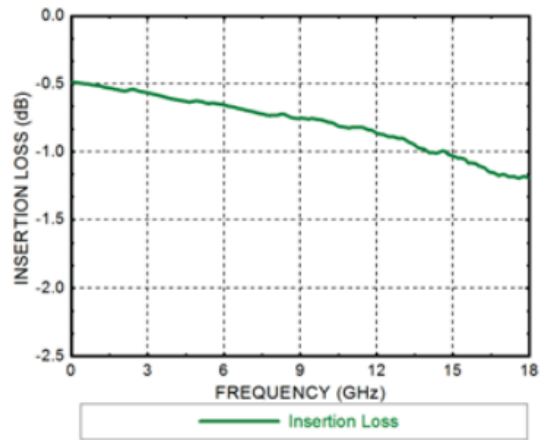
TA = +25°C, Vctl = 0/-5V

Parameters	Min.	Typ.	Max.	Units
Frequency	0.5-18			GHz
Insertion Loss		1		dB
Attenuation Range	15.00	15.25	15.50	dB
Attenuation Accuracy		± 0.3		dB
Return Loss		20		dB
Input 1dB Compression (P1dB)		24		dBm
Switching Speed		30		ns

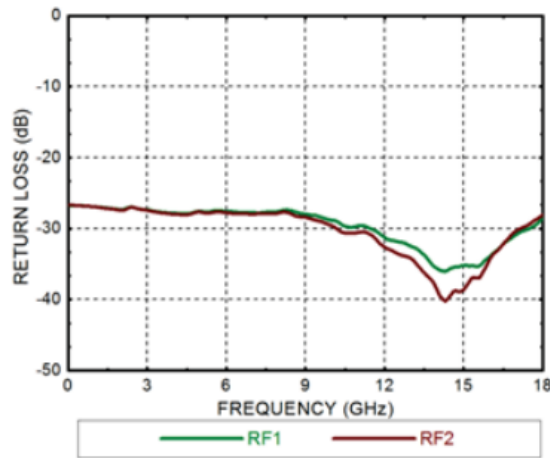
Attenuation



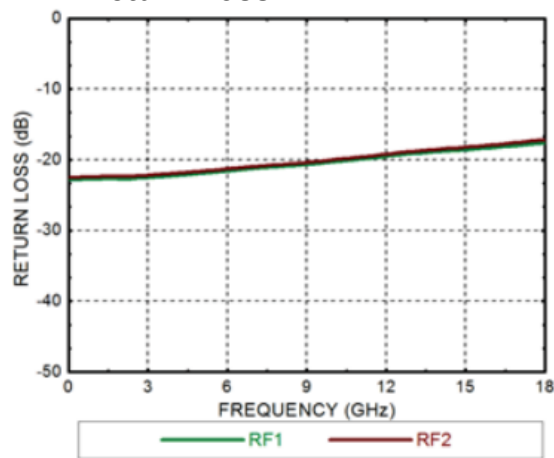
Insertion Loss



Return Loss



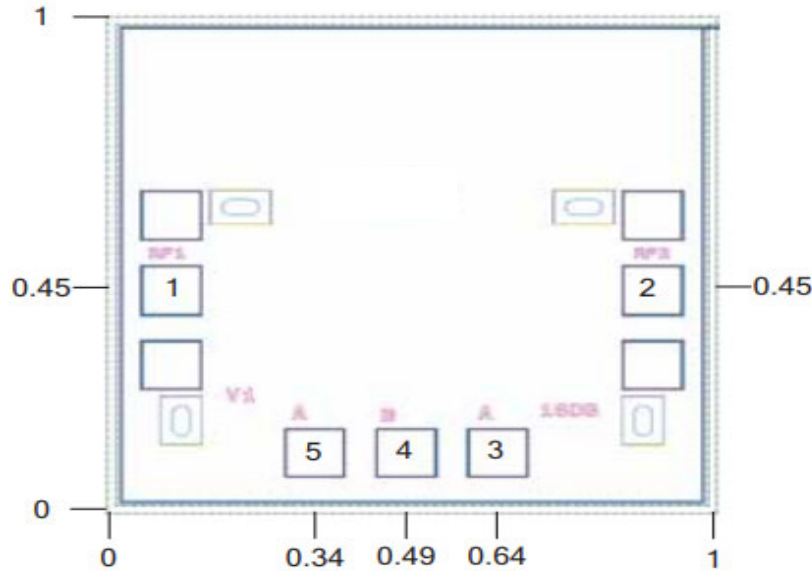
Return Loss





Outline Drawing:

All Dimensions in mm

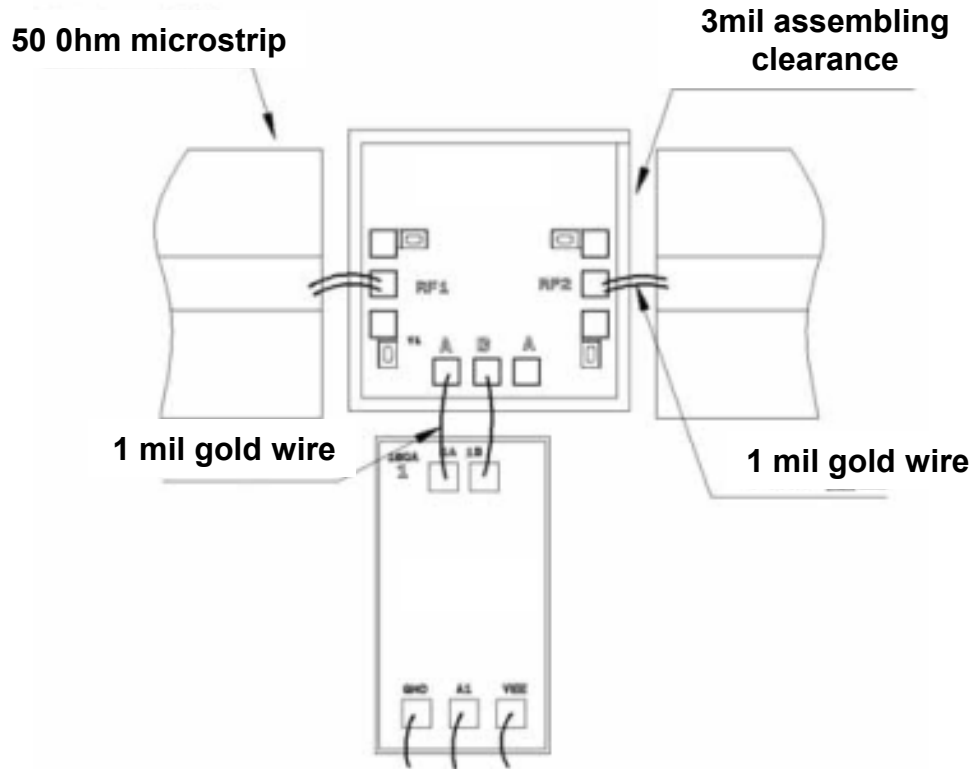


Pad Description

PAD	Function	Description
1	RF1	This pad is RF port and matched to 50Ω Impedance.
2	RF2	This pad is RF port and matched to 50Ω Impedance.
3,4,5	A,B,A	A = -5 V, B = 0 V, pass-through; A=0V,B= -5V, decaying 16dB.
Die Bottom	GND	Die bottom must be connected to RF/DC ground.



Assembly Drawing



Notes:

1. Die thickness: 100um
2. Typical bond pad is 100*100 μm^2
3. Bond pad metalization: Gold
4. Backside metalization: Gold
5. Backside of the die (GND)
6. No connection required for unlabeled bond pads

Maximum Ratings:

1. RF input power: +24dBm
2. Storage temperature: -65°C to +175°C
3. Operating temperature: -55°C to +85°C